

PT58



- / Aluminum die-casting structure for strong & stable operation.
- / Easy access/service M.2 SSD cover.
- / Rubber gasket frame sealing bezel design for IP-54 resistance.
- / Comprehensive dual-side mounting support of peripherals - MSR/Fingerprint/iButton/RFID/2D scanner readers.
- / Support 10.1" 2nd display & 2x20 LCM.
- / Innovative heat-dissipation fan-less operation design.
- / 4.8mm Super Slim Edge Bezel.

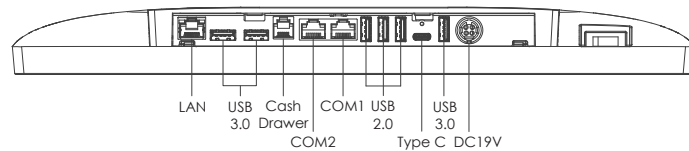


Poindus
COMPAL GROUP

Specifications

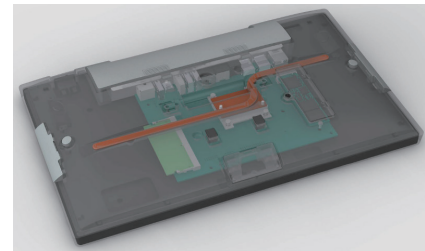
PT58		
System	Motherboard	PE24
	Processor	Intel® Elkhart Lake Celeron® J6412 @ 2.0GHz, up to 2.60 GHz
	Chipset	Chipset integrated
	System Memory	1 x 8GB DDR4 SO-DIMM memory (Max. support up to 16GB)
	Storage Device	1x128GB M.2 SSD as standard
	TPM	Intel F/W
LCD Touch Panel	LCD Size	15.6" 16:9 TFT LCD
	Brightness	250 nits
	Resolution	1920 x 1080, Full HD
	Touch Screen	Super slim bezel true-Flat PCAP multi-USB Port
External I/O Ports	COM Port	2 x COM (RJ48 connectors that support DC+0/5/12v by BIOS setting, default setting is 0v)
	LAN Port	1 x Gigabit Ethernet by RJ-45
	Cash Drawer	1 x RJ11 (supports 2 cash drawers), DC 24V/12V by Jumper setting
	External I/O Ports	Type-C 1 x Type-C (DP+PD)
	External I/O Ports	DC-Jack 1 x DC-jack with lock
Audio	Power Button	1
	Internal Speaker	2 x 2W
Construction	Construction	Die-cast aluminum housing with plastic covers
	Power	LED Indicator 1 for Power LED
Peripheral (USB Interface)	Power Adapter	65W adaptor, DC+19V
	Peripheral (USB Interface)	iButton reader / RFID reader / Fingerprint reader / 2D scanner
	Peripheral (USB Interface)	2x20 character LCM / 3-Track MSR
	Peripheral (USB Interface)	USB interface / 10.1" Resolution 1280 x 800 (16:10 wide screen), USB interface
Certificate		CE/FCC/LVD
Dimensions (W x H x D)		361.6 x 300.5 x 191.9 mm
Environment	Operating Temperature	0 ~ 40°C
	OS Supported	Windows 10 & 11 (64 bit)

IO Panels (PE24)

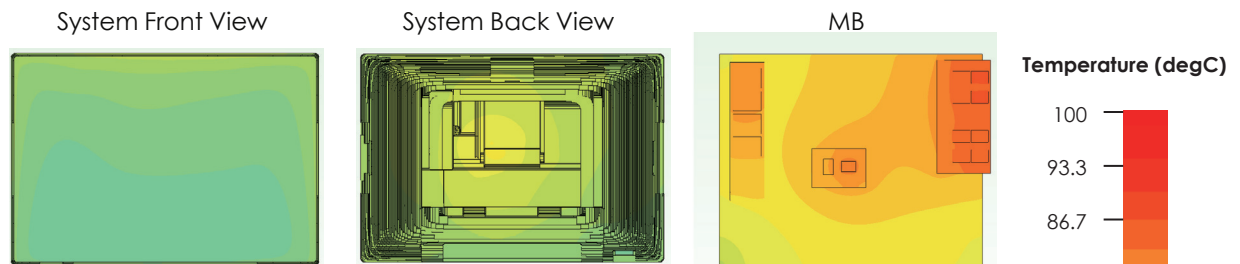


Heat-Dissipation Solution

Utilize the entire back cover as a heatsink to dissipate CPU & system heat from the inside out.



Without heat-dissipation solution



With heat-dissipation solution

